AMENDMENT TO THE CLAIMS

- 1.(**Original**) Infrared blocking powder, which is produced by forming a mixture of an indium salt, an antimony salt, and a tin salt in a mixing ratio of 15 to 90 wt%: 1 to 20 wt%: 5 to 80 wt%, dissolving the mixture in water, adding a growth inhibitor and a basic solution into the water having the dissolved mixture to precipitate powder, rinsing the powder, drying the rinsed powder, and sintering the dried powder.
- 2.(**Original**) The infrared blocking powder as set forth in claim 1, wherein the indium salt, the antimony salt and the tin salt are indium nitrate (In(NO₃)₃), antimony chloride (SbCl₃) and tin chloride (SnCl₂), respectively.
- 3.(**Original**) The infrared blocking powder as set forth in claim 1, wherein the sintering of the dried powder is conducted at 400 to 1000□ under an oxygen-free hydrogen atmosphere.
- 4.(Currently Amended) Infrared blocking solution, comprising:

the infrared blocking powder according to any one of claims 1 to 3 claim 1, dispersed in a solvent, the solvent being selected from the group consisting of alcohol, water, an organic solvent, and a mixture thereof.

5.(Original) The infrared blocking solution as set forth in claim 4, wherein the infrared blocking powder has a particle size of 5 to 200 nm.

6.(Currently Amended)Infrared blocking solution, comprising:

the infrared blocking powder according to any one of claims 1 to 3 claim 1;

solvent;

conductive polymer;

organic dispersion agent; and

photoinitiator.

7.(Original) The infrared blocking solution as set forth in claim 6, wherein the infrared blocking powder has a particle size of 5 to 200 nm.

8.(Original) The infrared blocking solution as set forth in claim 6, wherein a content of the infrared blocking powder is 5 to 70 wt% in the infrared blocking solution.

9.(**Original**) Infrared blocking material, which is produced by coating the infrared blocking solution according to claim 6 on a surface of a base.

10.(**Original**) The infrared blocking material as set forth in claim 9, wherein an adhesive layer is formed on any one side of the infrared blocking material coated on the base.

11.(**New**) Infrared blocking solution, comprising:

the infrared blocking powder according claim 2, dispersed in a solvent, the solvent being selected from the group consisting of alcohol, water, an organic solvent, and a mixture thereof.

12.(New) Infrared blocking solution, comprising:

the infrared blocking powder according claim 3, dispersed in a solvent, the solvent being selected from the group consisting of alcohol, water, an organic solvent, and a mixture thereof.

13.(**New**) Infrared blocking solution, comprising:

the infrared blocking powder according claim 2;

solvent;

conductive polymer;

organic dispersion agent; and

photoinitiator.

14.(**New**) Infrared blocking solution, comprising:

the infrared blocking powder according claim 3;

solvent;

conductive polymer;

organic dispersion agent; and

photoinitiator.